



SOT1380-6

WLCSP6, , wafer level chip-size package; 6 terminals; 0.4 mm pitch; 1.18 mm x 0.84 mm x 0.455 mm body (backside coating included)

24 February 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP6
Package type industry code	WLCSP6
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	04-12-2020
Manufacturer package code	98ASA01666D

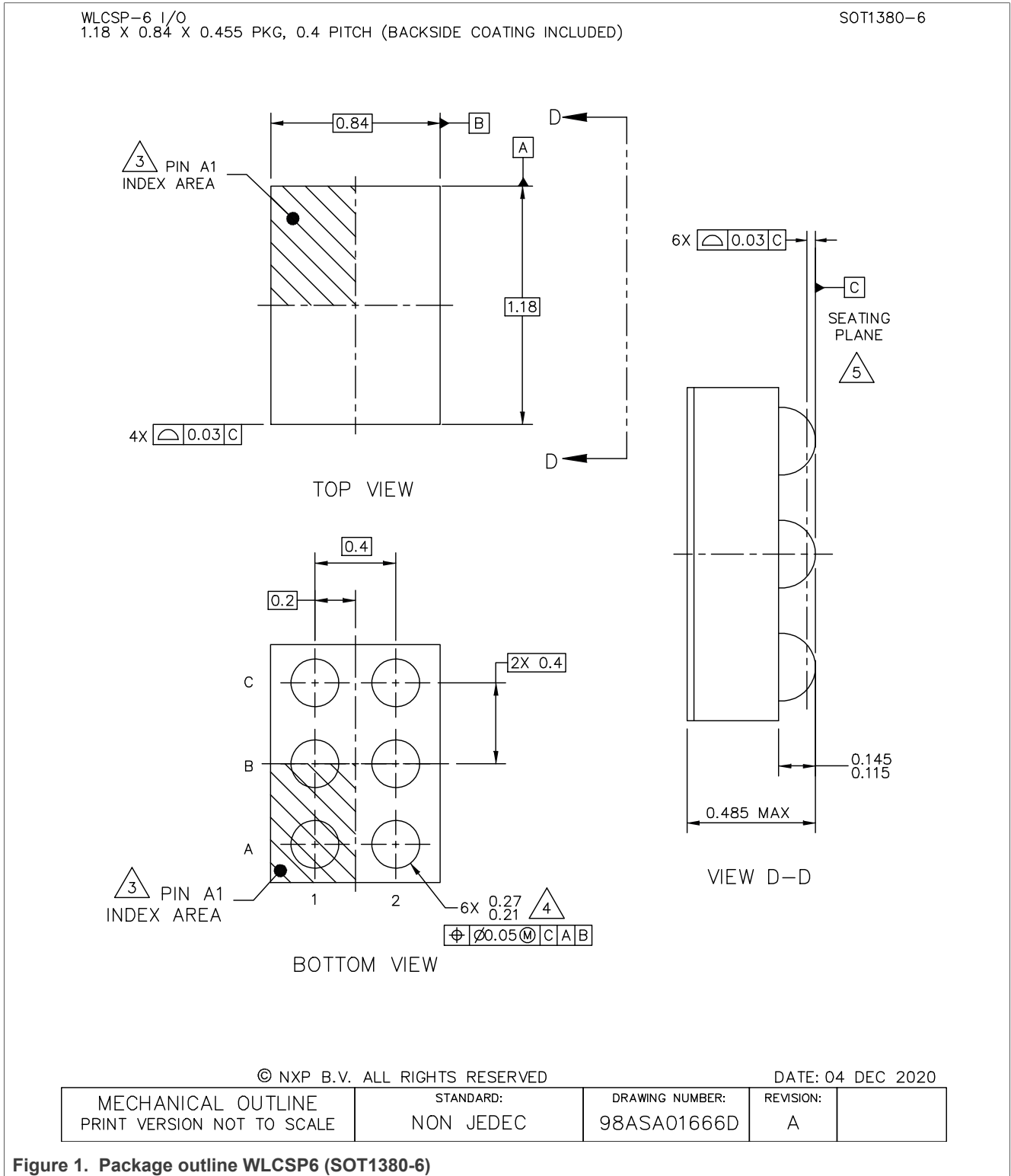
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.15	1.18	1.21	mm
package width	0.81	0.84	0.87	mm
package height	-	0.455	0.485	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	6	-	



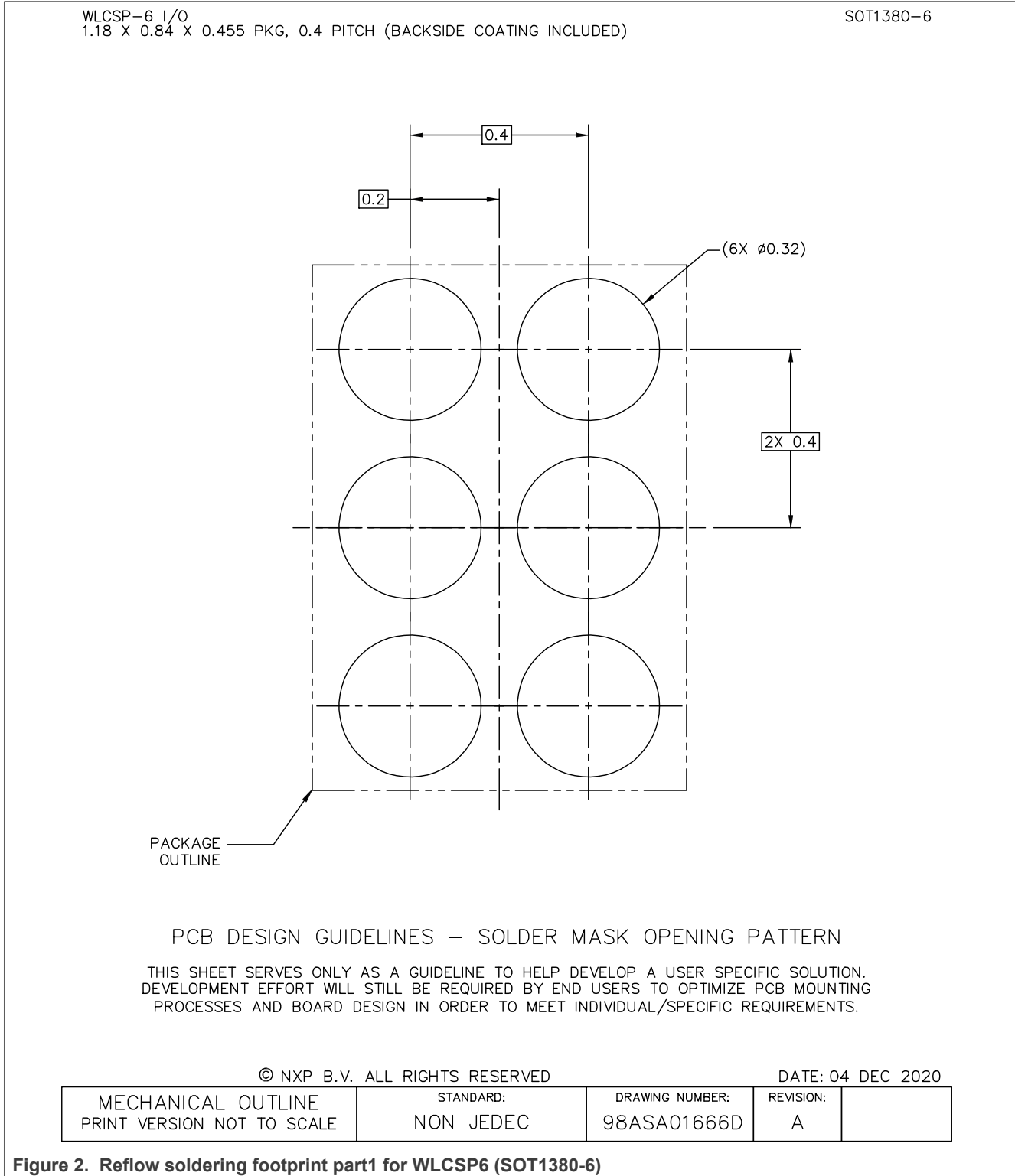
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2 Package outline



WLCSP6, , wafer level chip-size package; 6 terminals; 0.4 mm pitch; 1.18 mm x 0.84 mm x 0.455 mm body (backside coating included)

3 Soldering



WLCSP6, , wafer level chip-size package; 6 terminals; 0.4 mm pitch; 1.18 mm x 0.84 mm x 0.455 mm body (backside coating included)

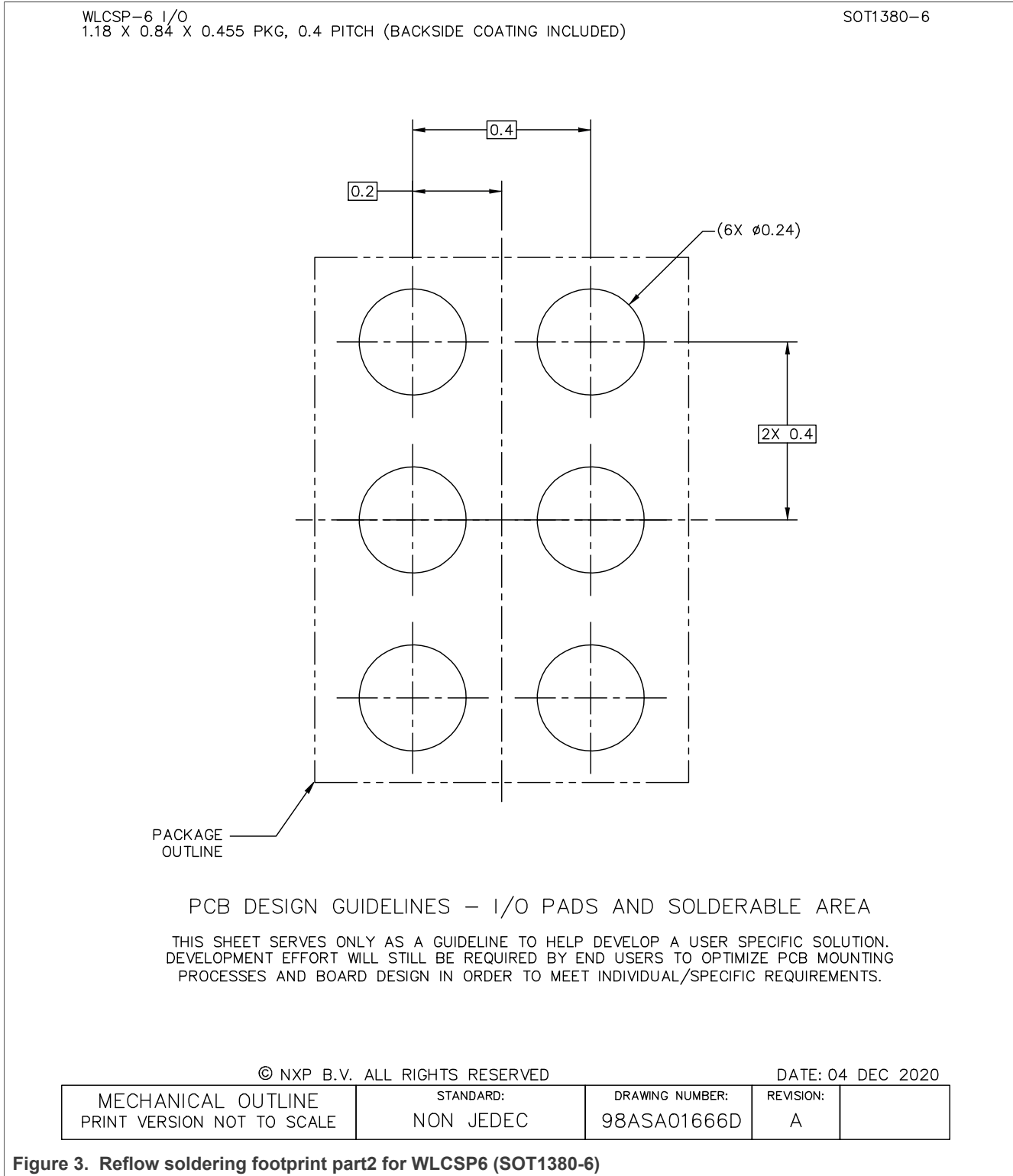


Figure 3. Reflow soldering footprint part2 for WLCSP6 (SOT1380-6)

WLCSP6, , wafer level chip-size package; 6 terminals; 0.4 mm pitch; 1.18 mm x 0.84 mm x 0.455 mm body (backside coating included)

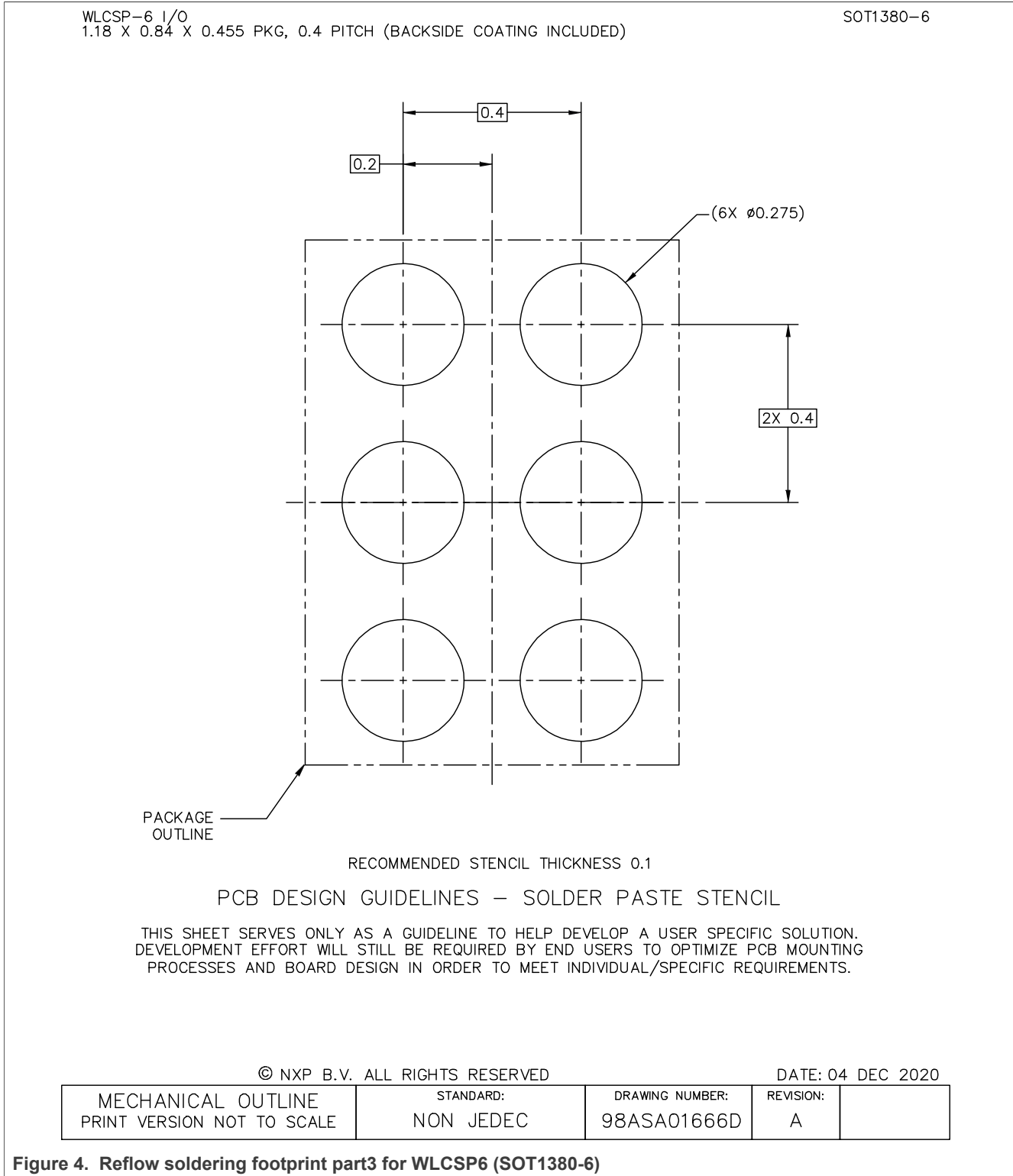


Figure 4. Reflow soldering footprint part3 for WLCSP6 (SOT1380-6)

WLCSP6, , wafer level chip-size package; 6 terminals; 0.4 mm pitch; 1.18 mm x 0.84 mm x 0.455 mm body (backside coating included)

WLCSP-6 I/O
1.18 X 0.84 X 0.455 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1380-6

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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DATE: 04 DEC 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01666D	REVISION: A	
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Figure 5. Package outline note WLCSP6 (SOT1380-6)

WLCSP6, , wafer level chip-size package; 6 terminals; 0.4 mm pitch; 1.18 mm x 0.84 mm x 0.455 mm
body (backside coating included)

4 Legal information

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